N25S818HA

256 kb L P e Se ial SRAM

32 k x 8 Bit Organization

Introduction

Table 6. TIMING TEST CONDITIONS

Item	
	– °

Table 7. TIMING

Item	Symbol	Min	Max	Units

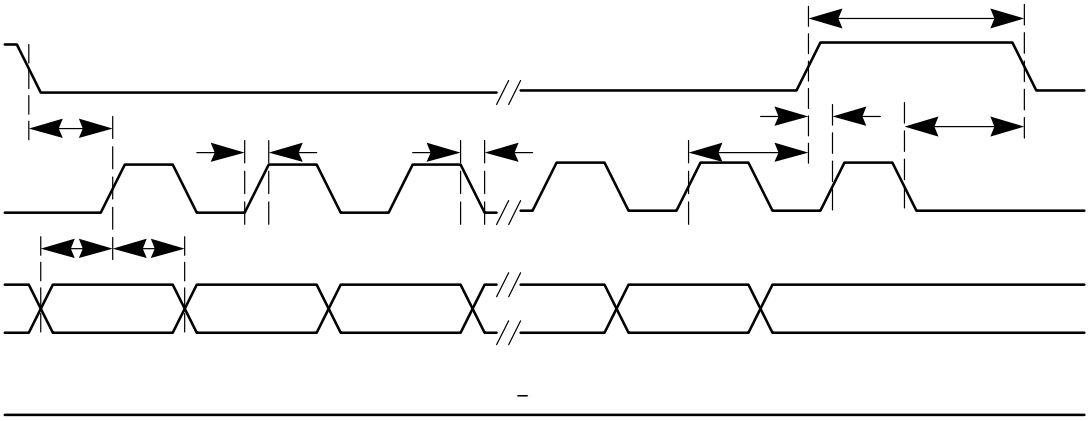


Figure 3. Serial Input Timing

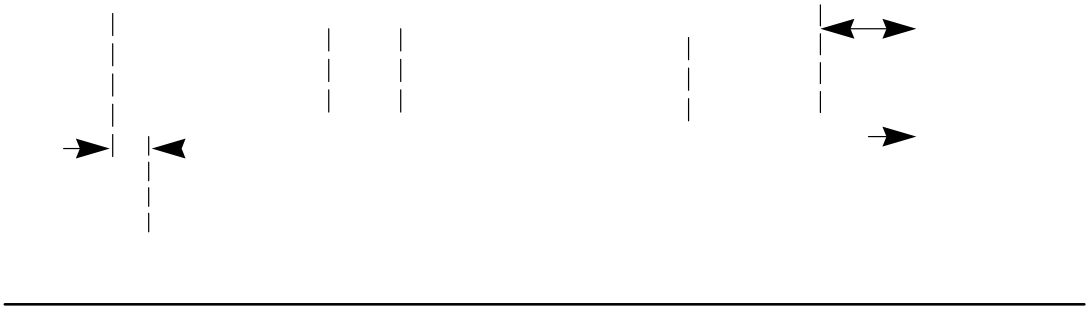
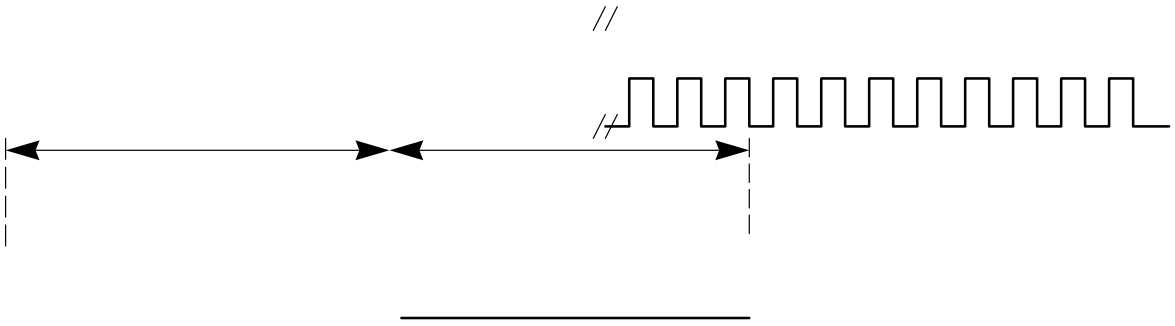


Table 8. CONTROL SIGNAL DESCRIPTIONS



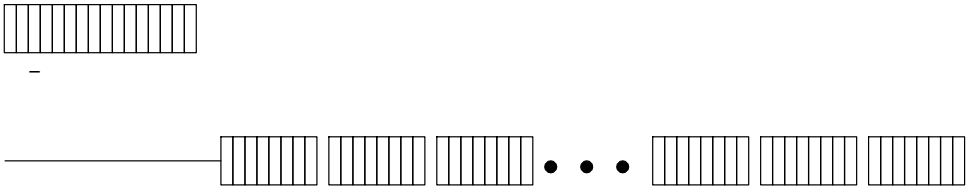


Figure 8. Page READ Sequence

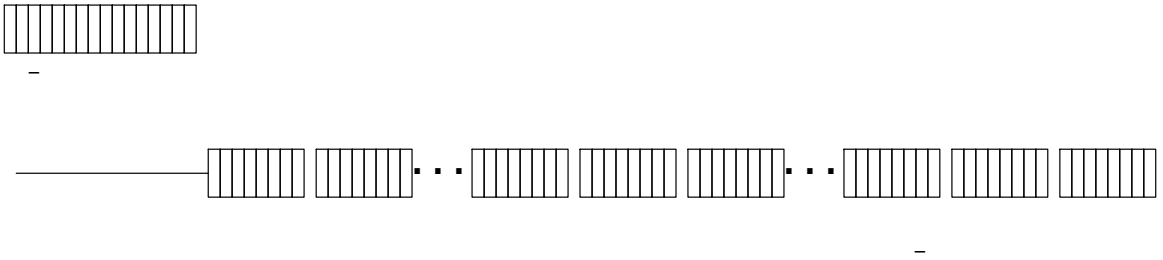


Figure 9. Burst READ Sequence

WRITE Operations

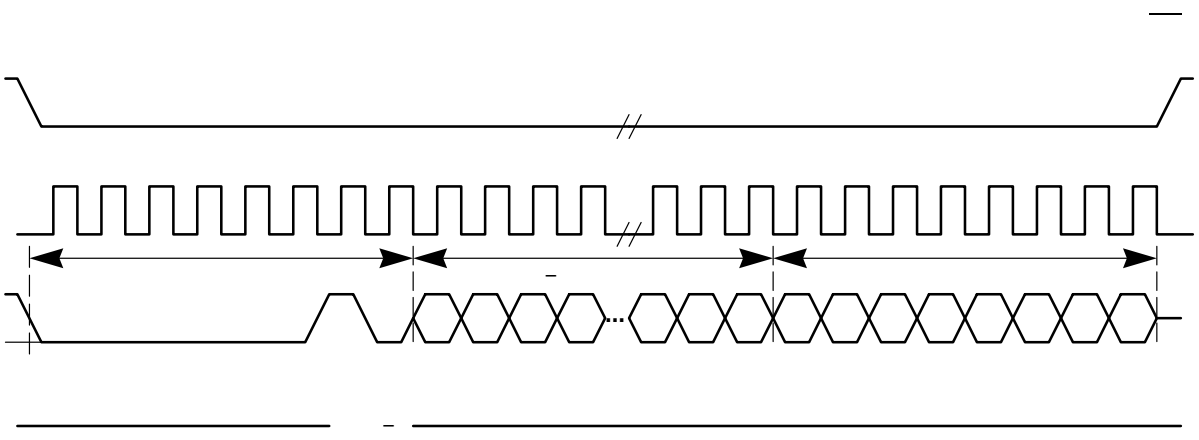
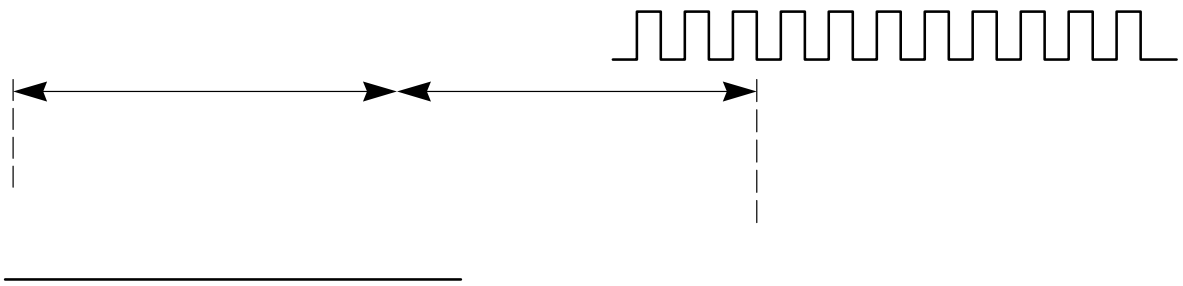


Figure 10. Word WRITE Sequence



WRITE Status Register Instruction (WRSR)

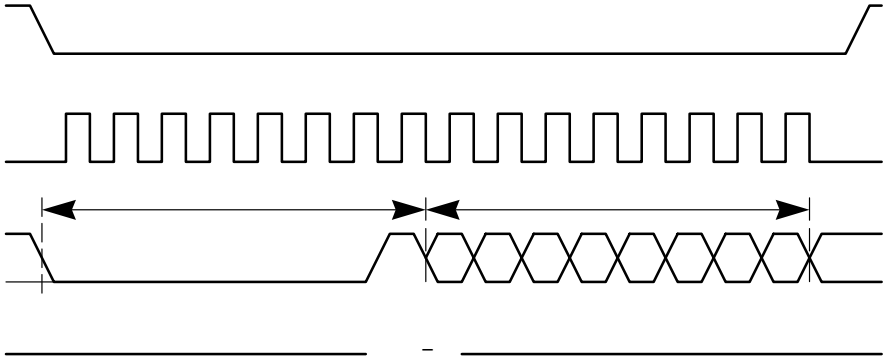


Figure 14. WRITE Status Register Sequence

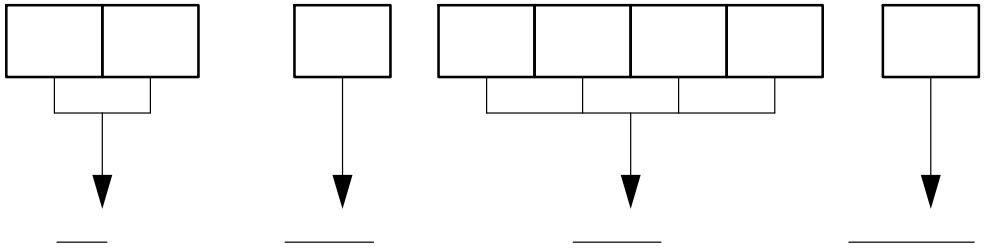
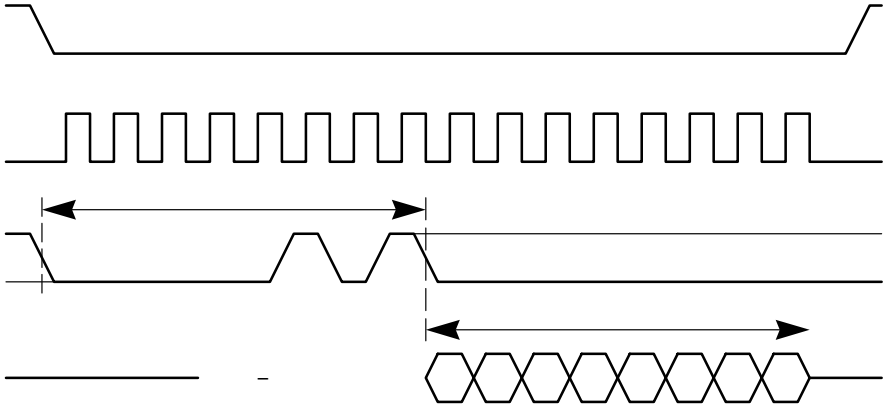


Figure 15. Status Register

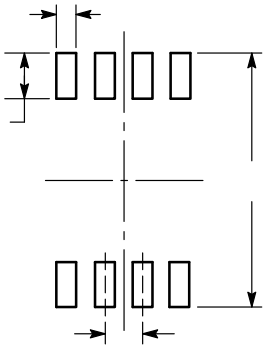
READ Status Register Instruction (RDSR)



SCALE 1:1

SOIC 8

RECOMMENDED
SOLDERING FOOTPRINT*

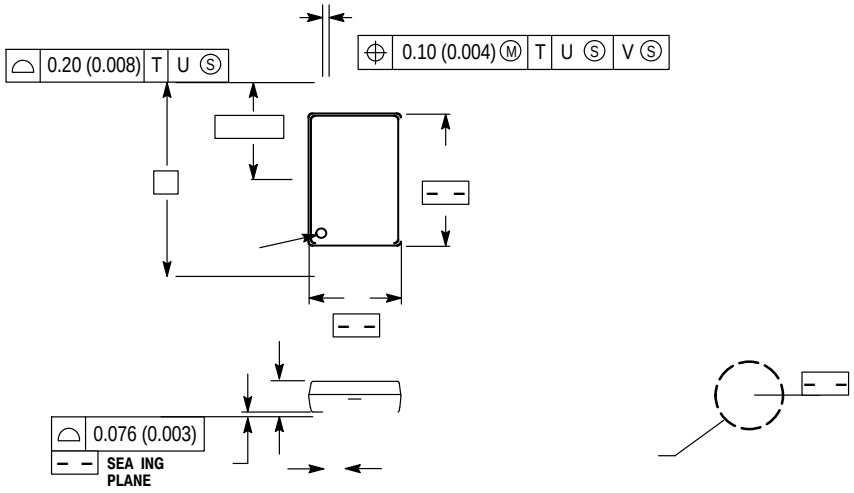


onsemi

–

CASE 948S
ISSUE C

DATE 20 JUN 2008



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIME ERS		INCHES	
DIM	MIN	MA	MIN	MA
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.10	---	0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.70	0.020	0.028
G	0.65 BSC		0.026 BSC	

L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°